SiR574DP

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PRODUCT SUMMARY	
V <sub>DS</sub> (V)	150
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS}$ = 10 V	0.0135
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS}$ = 7.5 V	0.0143
Q <sub>g</sub> typ. (nC)	23.6
I <sub>D</sub> (A)	48.1
Configuration	Single

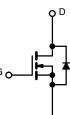
## **FEATURES**

N-Channel 150 V (D-S) MOSFET

- TrenchFET<sup>®</sup> Gen V power MOSFET
- Very low R<sub>DS</sub> x Q<sub>g</sub> figure-of-merit (FOM)
- Tuned for the lowest R<sub>DS</sub> x Q<sub>oss</sub> FOM
- 100 %  $R_{\alpha}$  and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

## **APPLICATIONS**

- Synchronous rectification
- · Primary side switch
- DC/DC converters
- Power supplies
- Motor drive control



N-Channel MOSFET

ORDERING INFORMATION				
Package	PowerPAK SO-8			
Lead (Pb)-free and halogen-free	SIR574DP-T1-RE3			
Alternate manufacturing location	SIR574DP-T1-BE3			

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V <sub>DS</sub>	150	v	
Gate-source voltage		V <sub>GS</sub>	± 20	v	
Continuous drain current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C		48.1		
	T <sub>C</sub> = 70 °C		38.4		
	T <sub>A</sub> = 25 °C	ID	12.1 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C	1	9.7 <sup>b, c</sup>		
Pulsed drain current (t = 100 µs)		I <sub>DM</sub>	150	— A	
Continuous source-drain diode current	T <sub>C</sub> = 25 °C		71		
	T <sub>A</sub> = 25 °C	I <sub>S</sub>	4.5 <sup>b, c</sup>		
Single pulse avalanche current		I <sub>AS</sub>	15		
Single pulse avalanche energy	L = 0.1 mH	E <sub>AS</sub>	11.25	mJ	
Maximum power dissipation	T <sub>C</sub> = 25 °C		78		
	T <sub>C</sub> = 70 °C		50		
	T <sub>A</sub> = 25 °C	PD	5 <sup>b, c</sup>	W	
	T <sub>A</sub> = 70 °C	1	3.2 <sup>b, c</sup>		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stq</sub>	-55 to +150	*0	
Soldering recommendations (peak temperature) <sup>c</sup>		9	260		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b	t ≤ 10 s	R <sub>thJA</sub>	20	25	°C/W	
Maximum junction-to-case (drain)	Steady state	R <sub>thJC</sub>	1.3	1.6	C/W	

## Notes

a. Package limitedb. Surface mounted on 1" x 1" FR4 board

c. t = 10 s

d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

f. Maximum under steady state conditions is 65 °C/W

g. T<sub>C</sub> = 25 °C

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**FREE** <u>doc?99912</u> ۲<sup>D</sup>

**RoHS** 

HALOGEN

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SiR574DP

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static	• •		<u> </u>				
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 1 mA$	150	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 10 mA	-	100	-		
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-6.7	-	mV/°C	
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	2	-	4	V	
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	100	nA	
Zero gate voltage drain current		$V_{DS} = 120 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1		
	IDSS	$V_{DS}$ = 120 V, $V_{GS}$ = 0 V, $T_{J}$ = 70 °C	-	-	15	μA	
Drain-source on-state resistance <sup>a</sup>	_	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	-	0.0112	0.0135		
	R <sub>DS(on)</sub>	$V_{GS} = 7.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	-	0.0119	0.0143	Ω	
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	-	45	-	S	
Dynamic <sup>b</sup>			•		•		
Input capacitance	Ciss	V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	2300	-	pF	
Output capacitance	C <sub>oss</sub>		-	205	-		
Reverse transfer capacitance	C <sub>rss</sub>		-	8.4	-		
Tatal asta akawa	0	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	31.5	48	nC	
Total gate charge	Qg	$V_{DS} = 75 \text{ V}, V_{GS} = 7.5 \text{ V}, I_D = 10 \text{ A}$	-	23.6	36		
Gate-source charge	Q <sub>gs</sub>		-	11.6	-		
Gate-drain charge	Q <sub>gd</sub>		-	3.7	-		
Output charge	Q <sub>oss</sub>	V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V -		68	-		
Gate resistance	R <sub>g</sub>	f = 1 MHz	0.4	1.0	1.8	Ω	
Turn-on delay time	t <sub>d(on)</sub>		-	15	30		
Rise time	t <sub>r</sub>	$\label{eq:VDD} \begin{array}{l} V_{DD} = 75 \; V, \; R_L = 7.5 \; \Omega, \; I_D \cong 10 \; A, \\ V_{GEN} = 10 \; V, \; R_g = 1 \; \Omega \end{array}$	-	7	14		
Turn-off delay time	t <sub>d(off)</sub>		-	24	48		
Fall time	t <sub>f</sub>		-	9	18		
Turn-on delay time	t <sub>d(on)</sub>		-	18	36	ns	
Rise time	t <sub>r</sub>	$\begin{array}{l} V_{DD} = 75 \; V, \; R_L = 7.5 \; \Omega, \; I_D \cong 10 \; A, \\ V_{GEN} = 7.5 \; V, \; R_g = 1 \; \Omega \end{array}$	-	9	18		
Turn-off delay time	t <sub>d(off)</sub>		-	22	44		
Fall time	t <sub>f</sub>		-	9	18		
Drain-Source Body Diode Characteristi	cs		•		•		
Continuous source-drain diode current	Is	T <sub>C</sub> = 25 °C	-	-	71	•	
Pulse diode forward current	I <sub>SM</sub>		-	-	150	A	
Body diode voltage	V <sub>SD</sub>	$I_{\rm S} = 5$ A, $V_{\rm GS} = 0$ V	-	0.78	1.1	V	
Body diode reverse recovery time	t <sub>rr</sub>		-	68	136	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>	I <sub>F</sub> = 10 A, di/dt = 100 A/µs,	-	143	286	nC	
Reverse recovery fall time	t <sub>a</sub>	$T_J = 25 \ ^\circ C$	-	53	-		
•	t <sub>b</sub>		-	15	-	ns	

Notes

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %

b. Guaranteed by design, not subject to production testing

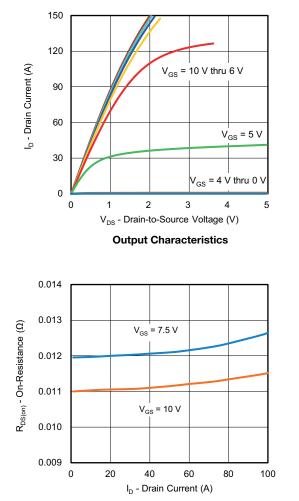
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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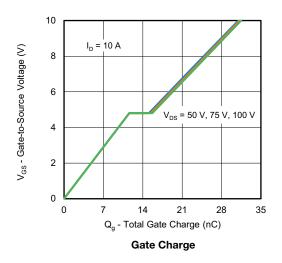
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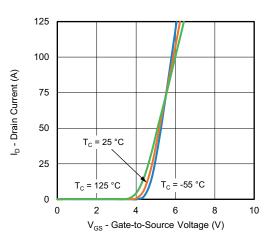


# TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

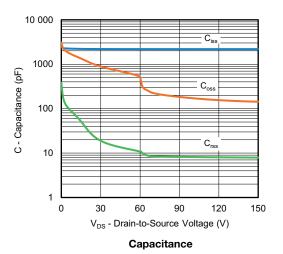


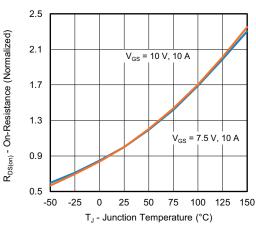
**On-Resistance vs. Drain Current and Gate Voltage** 





Transfer Characteristics





**On-Resistance vs. Junction Temperature** 

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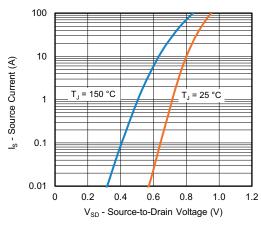
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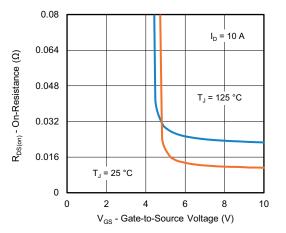
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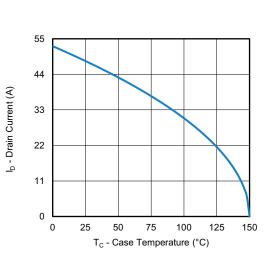
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Source-Drain Diode Forward Voltage



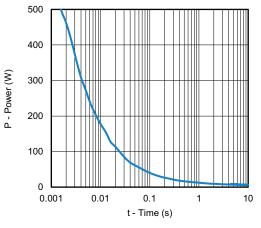
On-Resistance vs. Gate-to-Source Voltage



Safe Operating Area, Junction-to-Ambient

#### 0.6 0.3 V<sub>GS(th)</sub> - Variance (V) 0 I<sub>D</sub> = 5 mA -0.3 -0.6 I<sub>D</sub> = 250 μA -0.9 -1.2 -50 -25 0 100 125 25 50 75 150 T<sub>J</sub> - Junction Temperature (°C)

**Threshold Voltage** 



Single Pulse Power, Junction-to-Ambient

#### Note

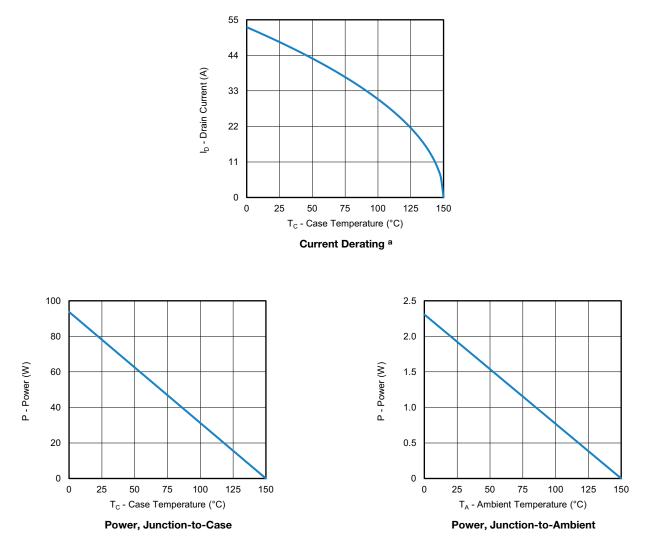
a. V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

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# TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### Note

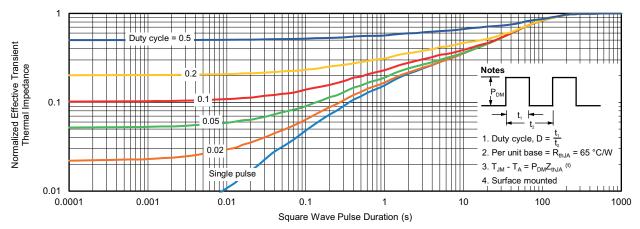
a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



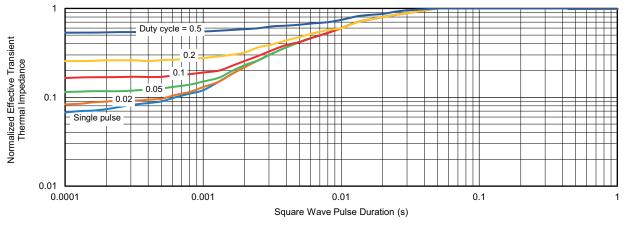
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# TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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